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### Push Pin Attachment Method

Part Number: 10 - 6327 - 01G RoHS V Change Change Notice

Printer Friendly Version Download our BGA Brochure (PDF)

This is a popular item and should be available at Aavid Thermalloy 's authorized distributors

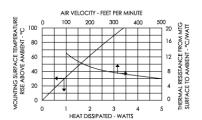
Find your Tocal distributor								
BGA Surface	Interface	Heat Sink Finish						
All	None	Black Anodize						

#### **Features and Benefits**

- Simple tool -free installation
- Springs maintain constant and uniform pressure to ensure reliable thermal contact
- Mechanical attachment provides secure mounting where vibration is a concern
- Fits industry Standard Hole patterns
- Accommodates up to 4mm stack height (typical 1.5mm PCB and 2.5 mm BGA package)
- Pin Fin array allows omni directional airflow to maximize heat dissipation

Width	Length	Height	Fin Thickness Across Width	Fin Thickness Across Length	Base Thickness	# of fins across width	# of fins across length
28.5mm	28.5mm	10mm	1.50mm	2.10mm	1.75mm	10	9

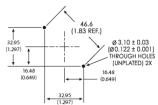
### **Mechanical Outline Drawing**



Unless otherwise shown, tolerances are

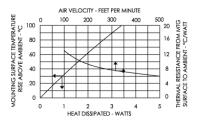
± 0.38( ± .015)

# Recommended PCB Hole Pattern



## Thermal Performance





<sup>\*</sup> Natural convection thermal resistance is based on a 75 °C heat sink temperature rise.

This data sheet represents only one of a broad range of products we make to cool electronics. Our representatives can help you configure a complete cooling solution for your individual applications.

For more information on how to put our strengths to work for you, contact your local sales

http://www.aavidthermalloy.com/sales/reps.shtml

<sup>\*\*</sup> Forced convection thermal resistance based on an entering 1.0 m/s (200 lfm) airflow. Due to various heat dissipation paths within a BGA device, please test the heat sink in your application.